

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Original) A semiconductor device characterized by comprising:
a silicon substrate;
an antenna made of gold;
an insulating layer; and
an integrated circuit formed on a surface of said silicon substrate for processing information to be transmitted/received from said antenna,
wherein said antenna, insulating layer and integrated circuit are laminated in this order on the surface of said silicon substrate, a thickness of said semiconductor substrate is set to 200 μm or thinner, and a width and a thickness of said antenna are set to 2.6 μm or larger and 10 μm or smaller.

2. (Original) A semiconductor device characterized by comprising:
an antenna made of gold;
an insulating layer; and
an integrated circuit formed on a surface of a silicon substrate for processing information to be transmitted/received from said antenna,
wherein said antenna, insulating layer and integrated circuit are laminated in this order, a thickness of said semiconductor substrate is a thickness of said integrated circuit or is set thinner than 50 μm .

3. (Original) The semiconductor apparatus according to claim 1 or 2, wherein electrode portions for connecting said antenna and said integrated circuit are formed in areas where said resin layer is formed in a tapered shape.

4. (Currently Amended) The semiconductor apparatus according to ~~any one of claims 1 to 3~~ claim 1 or 2, wherein said antenna has a thickness and a width not presenting a skin depth effect by electronic magnetic waves used by communications, and the width is narrower than 10 μm .

5. (Currently Amended) The semiconductor apparatus according to ~~any one of claims 1 to 4~~ claim 1 or 2, further comprising a tape coated with an adhesive layer, and a side of said antenna of said semiconductor device is adhered to said adhesive layer.

6. (Original) The semiconductor apparatus according to claim 3, wherein a radiation antenna is connected in place of said antenna.

7. (Currently Amended) A paper sheet characterized by comprising:
the semiconductor device recited in ~~any one of claims 1 to 5~~ claim 1 or 2; and
a protective member having a recess,
wherein the semiconductor device is threaded being included in said recess of said protective member.

8. (Currently Amended) A staple of a stapler characterized in that the semiconductor device ~~received~~ recited in any one of claims 1 to 5 and claim 7 claim 1 or 2 is

mounted on a surface or inside the staple of the stapler.

9. (Currently Amended) A manufacture method for the semiconductor device according to ~~claims 1 to 4~~ claim 1 or 2, characterized by comprising a step of:
etching a wafer from a rear surface thereof to an oxide film inside the wafer to form separation grooves.